

April 2006

# 2N5551- MMBT5551 NPN General Purpose Amplifier

### **Features**

- This device is designed for general purpose high voltage amplifiers and gas discharge display drivers.
- Suffix "-C" means Center Collector in 2N5551 (1. Emitter 2. Collector 3. Base)
- Suffix "-Y" means  $h_{FE}$  180~240 in 2N5551 (Test condition :  $I_C$  = 10mA,  $V_{CE}$  = 5.0V)





Absolute Maximum Ratings \* T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	160	V
$V_{CBO}$	Collector-Base Voltage	180	V
$V_{EBO}$	Emitter-Base Voltage	6.0	V
I <sub>C</sub>	Collector current - Continuous	600	mA
T <sub>J</sub> , T <sub>stg</sub>	Junction and Storage Temperature	-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

#### NOTES:

## Thermal Characteristics Ta=25°C unless otherwise noted

Symbol	Parameter	М	Units	
Symbol		2N5551	*MMBT5551	
P <sub>D</sub>	Total Device Dissipation Derate above 25°C	625 5.0	350 2.8	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Case	83.3		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	357	°C/W

<sup>\*</sup> Device mounted on FR-4 PCB 1.6"  $\times$  1.6"  $\times$  0.06."

<sup>1.</sup> These ratings are based on a maximum junction temperature of 150 degrees  $\ensuremath{\text{C}}.$ 

<sup>2.</sup> These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## **Electrical Characteristics** $T_a = 25$ °C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charact	eristics			1	
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage *	$I_C = 1.0 \text{mA}, I_B = 0$	160		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_E = 0$	180		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10uA, I_C = 0$	6.0		V
I <sub>CBO</sub>	Collector Cutoff Current	V <sub>CB</sub> = 120V, I <sub>E</sub> = 0 V <sub>CB</sub> = 120V, I <sub>E</sub> = 0, T <sub>a</sub> = 100°C		50 50	nA μA
I <sub>EBO</sub>	Emitter Cutoff Current	V <sub>EB</sub> = 4.0V, I <sub>C</sub> = 0		50	nA
On Charact	eristics				
h <sub>FE</sub>	DC Current Gain	$I_{C} = 1.0$ mA, $V_{CE} = 5.0$ V $I_{C} = 10$ mA, $V_{CE} = 5.0$ V $I_{C} = 5$ 0mA, $V_{CE} = 5.0$ V	80 80 30	250	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 10mA, I_B = 1.0mA$ $I_C = 50mA, I_B = 5.0mA$		0.15 0.20	V V
V <sub>BE(sat)</sub>	Base-Emitter On Voltage	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$ $I_C = 50\text{mA}, I_B = 5.0\text{mA}$		1.0 1.0	V V
Small Signa	al Characteristics				
f <sub>T</sub>	Current Gain Bandwidth Product	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V, f = 100MHz	100	300	MHz
C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0, f = 1.0MHz		6.0	pF
C <sub>ibo</sub>	Input Capacitance	$V_{BE} = 0.5V, I_{C} = 0, f = 1.0MHz$		20	pF
H <sub>fe</sub>	Small-Signal Current Gain	Ic = 1.0 mA, VcE = 10 V, f = 1.0kHz	50	250	
NF	Noise Figure	Ic = 250 uA, Vcε = 5.0 V, Rs=1.0 kΩ, f=10 Hz to 15.7 kHz		8.0	dB

## **Spice Model**

NPN (ls=2.511f Xti=3 Eg=1.11 Vaf=100 Bf=242.6 Ne=1.249 lse=2.511f lkf=.3458 Xtb=1.5 Br=3.197 Nc=2 lsc=0 lkr=0 Rc=1 Cjc=4.883p Mjc=.3047 Vjc=.75 Fc=.5 Cje=18.79p Mje=.3416 Vje=.75 Tr=1.202n Tf=560p ltf=50m Vtf=5 Xtf=8 Rb=10)

## **Typical Performance Characteristics**

Figure 1. Typical Pulsed Current Gain vs Collector Current

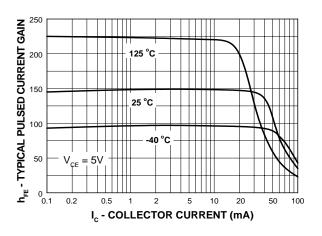


Figure 2. Collector-Emitter Saturation Voltage vs Collector Current

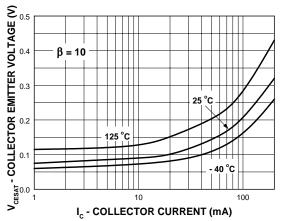


Figure 3. Base-Emitter Saturation Voltage vs Collector Current

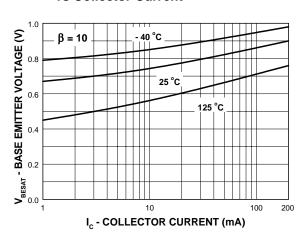


Figure 4. Base-Emitter On Voltage vs Collector Current

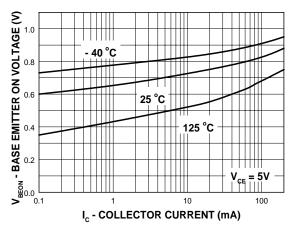


Figure 5. Collector Cutoff Current vs Ambient Temperature

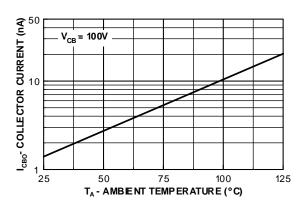
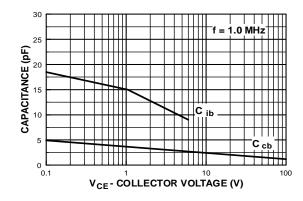
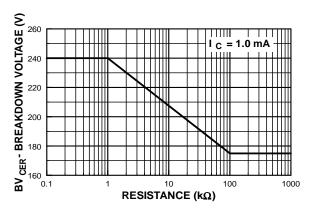


Figure 6. Input and Output Capacitance vs Reverse Voltage



## Typical Performance Characteristics (Continued)

Figure 7. Collector- Emitter Breakdown Voltage with Resistance Between Emitter-Base vs Collector Current



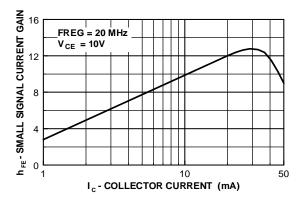
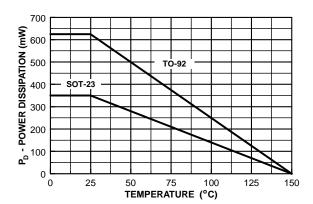


Figure 9. Power Dissipation vs Ambient Temperature



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EnSigna™	ImpliedDisconnect™	OCXPro™	μSerDes™	UHC™
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